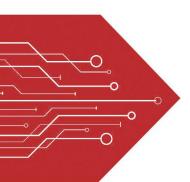
MSKSEMI















ESD

TVS

TSS

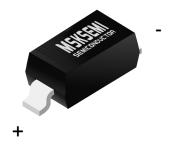
MOV

GDT

PLED

Broduct data sheet





SOD-123

FEATURES

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion
- For General Purpose Switching Applications
- High Conductance

Maximum Ratings and Electrical Characteristics, Single Diode @T_A=25℃

Parameter	Symbol	Limits	Unit	
Non-Repetitive Peak reverse voltage	V_{RM}	100	V	
Peak Repetitive Peak reverse voltage	V_{RRM}			
Working Peak Reverse Voltage	V_{RWM}	75	V	
DC Blocking Voltage	V_{R}			
RMS Reverse Voltage	$V_{R(RMS)}$	53	V	
Forward Continuous Current	I _{FM}	300	mA	
Average Rectified Output Current	Ιο	150	mA	
Peak forward surge current @=1.0µs	I _{FSM}	2.0	Α	
@=1.0s		1.0	A	
Power Dissipation	Pd	400	mW	
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	315	°C/W	
Junction temperature	Tj	125	°C	
Storage temperature	T _{STG}	-65~+150	°C	

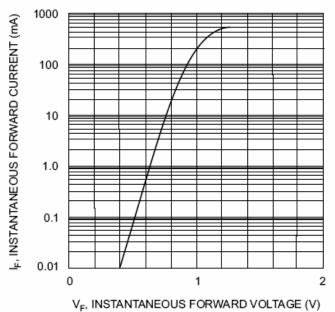
Electrical Ratings @T_A=25℃

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V _{F1}			0.715	V	I _F =1mA
	V _{F2}			0.855	V	I _F =10mA
	V _{F3}			1.0	V	I _F =50mA
	V _{F4}			1.25	V	I _F =150mA
Reverse current	I _{R1}			1	μA	V _R =75V
	I _{R2}			25	nA	V _R =20V
Capacitance between terminals	Ст			2	pF	V _R =0V,f=1MHz
Reverse Recovery Time	t _{rr}			4	ns	I _F =I _R =10mA
Neverse Necovery Time						Irr=0.1 XI_R , R_L =100 Ω



Typical Characteristics

1N4148W-7-MS/BAV16W-7-MF



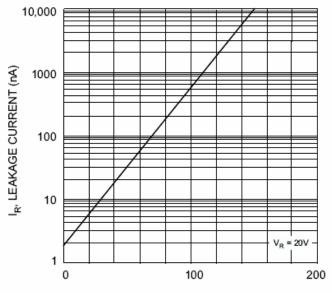
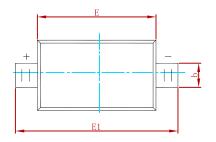


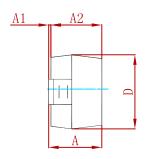
Fig. 1 Forward Characteristics

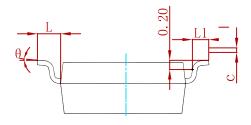
T_j, JUNCTION TEMPERATURE (°C) Fig. 2 Leakage Current vs Junction Temperature



PACKAGE MECHANICAL DATA

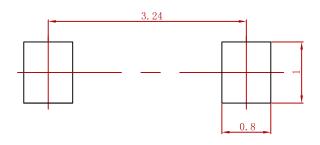






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.450	0.650	0.018	0.026	
С	0.080	0.150	0.003	0.006	
D	1.500	1.700	0.059	0.067	
Е	2.600	2.800	0.102	0.110	
E1	3.550	3.850	0.140	0.152	
Ĺ	0.500 REF		0.020 REF		
L1	0.250	0.450	0.010	0.018	
θ	0°	8°	0°	8°	

Suggested Pad Layout



- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY	MARK
1N4148W-7-MS	SOD-123	3000	T4
BAV16W-7-MS	SOD-123	3000	T6





- Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.
- MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specificationsof any andall MSKSEMI Semiconductor products described orcontained herein.
- Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.
- MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possiblethat these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuitsfor safedesign, redundant design, and structural design.
- In the event that any or all MSKSEMI Semiconductor products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.
- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.
- Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringementsof intellectual property rights or other rightsof third parties.
- Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor productthat you intend to use.